

MOSFET – Power, N-Channel, Logic Level, SOT-223

3.0 A, 60 V

NTF3055L108, NVF3055L108

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

Features

- NVF Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

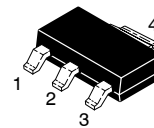
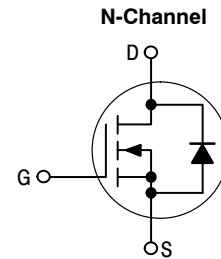
MAXIMUM RATINGS ($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	60	Vdc
Drain-to-Gate Voltage ($R_{GS} = 1.0\text{ M}\Omega$)	V_{DGR}	60	Vdc
Gate-to-Source Voltage	V_{GS}	± 15	Vdc
– Continuous		± 20	Vpk
– Non-repetitive ($t_p \leq 10\text{ ms}$)			
Drain Current	I_D	3.0	Adc
– Continuous @ $T_A = 25\text{ }^{\circ}\text{C}$ (Note 1)		1.4	Apk
– Continuous @ $T_A = 100\text{ }^{\circ}\text{C}$ (Note 2)		9.0	
– Single Pulse ($t_p \leq 10\text{ }\mu\text{s}$)			
Total Power Dissipation @ $T_A = 25\text{ }^{\circ}\text{C}$ (Note 1)	P_D	2.1	Watts
Total Power Dissipation @ $T_A = 25\text{ }^{\circ}\text{C}$ (Note 2)		1.3	Watts
Derate above $25\text{ }^{\circ}\text{C}$		0.014	W/ $^{\circ}\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to 175	$^{\circ}\text{C}$
Single Pulse Drain-to-Source Avalanche Energy - Starting $T_J = 25\text{ }^{\circ}\text{C}$ ($V_{DD} = 25\text{ Vdc}$, $V_{GS} = 5.0\text{ Vdc}$, $I_{L(pk)} = 7.0\text{ Apk}$, $L = 3.0\text{ mH}$, $V_{DS} = 60\text{ Vdc}$)	E_{AS}	74	mJ
Thermal Resistance	$R_{\theta JA}$	72.3	$^{\circ}\text{C/W}$
– Junction-to-Ambient (Note 1)	$R_{\theta JA}$	114	
– Junction-to-Ambient (Note 2)			
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	$^{\circ}\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- When surface mounted to an FR4 board using 1" pad size, 1 oz. (Cu. Area 1 in²).
- When surface mounted to an FR4 board using minimum recommended pad size, 2 oz. (Cu. Area 0.272 in²).

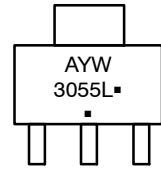
3.0 A, 60 V
 $R_{DS(on)} = 120\text{ m}\Omega$



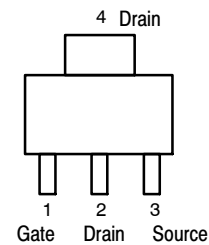
SOT-223
CASE 318E
STYLE 3

MARKING DIAGRAM

3055L = Device Code
A = Assembly Location
Y = Year
W = Work Week
■ = Pb-Free Package
(Note: Microdot may be in either location)



PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NTF3055L108, NVF3055L108

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage (Note 3) ($V_{GS} = 0\text{ Vdc}$, $I_D = 250\text{ }\mu\text{Adc}$) Temperature Coefficient (Positive)	$V_{(BR)DSS}$	60 –	68 68	– –	Vdc mV/ $^{\circ}\text{C}$
Zero Gate Voltage Drain Current ($V_{DS} = 60\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$) ($V_{DS} = 60\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 150\text{ }^{\circ}\text{C}$)	I_{DSS}	– –	– –	1.0 10	μAdc
Gate-Body Leakage Current ($V_{GS} = \pm 15\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	–	–	± 100	nAdc

ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage (Note 3) ($V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{Adc}$) Threshold Temperature Coefficient (Negative)	$V_{GS(th)}$	1.0 –	1.68 4.6	2.0 –	Vdc mV/ $^{\circ}\text{C}$
Static Drain-to-Source On-Resistance (Note 3) ($V_{GS} = 5.0\text{ Vdc}$, $I_D = 1.5\text{ Adc}$)	$R_{DS(on)}$	–	92	120	m Ω
Static Drain-to-Source On-Resistance (Note 3) ($V_{GS} = 5.0\text{ Vdc}$, $I_D = 3.0\text{ Adc}$) ($V_{GS} = 5.0\text{ Vdc}$, $I_D = 1.5\text{ Adc}$, $T_J = 150\text{ }^{\circ}\text{C}$)	$V_{DS(on)}$	–	0.290 0.250	0.43 –	Vdc
Forward Transconductance (Note 3) ($V_{DS} = 7.0\text{ Vdc}$, $I_D = 3.0\text{ Adc}$)	g_{fs}	–	5.7	–	Mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	$(V_{DS} = 25\text{ Vdc}$, $V_{GS} = 0\text{ V}$, $f = 1.0\text{ MHz}$)	C_{iss}	–	313	440	pF
Output Capacitance		C_{oss}	–	112	160	
Transfer Capacitance		C_{rss}	–	40	60	

SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	$(V_{DD} = 30\text{ Vdc}$, $I_D = 3.0\text{ Adc}$, $V_{GS} = 5.0\text{ Vdc}$, $R_G = 9.1\text{ }\Omega$) (Note 3)	$t_{d(on)}$	–	11	25	ns
Rise Time		t_r	–	35	70	
Turn-Off Delay Time		$t_{d(off)}$	–	22	45	
Fall Time		t_f	–	27	60	
Gate Charge	$(V_{DS} = 48\text{ Vdc}$, $I_D = 3.0\text{ Adc}$, $V_{GS} = 5.0\text{ Vdc}$) (Note 3)	Q_T	–	7.6	15	nC
		Q_1	–	1.4	–	
		Q_2	–	4.0	–	

SOURCE-DRAIN DIODE CHARACTERISTICS

Forward On-Voltage	$(I_S = 3.0\text{ Adc}$, $V_{GS} = 0\text{ Vdc}$) $(I_S = 3.0\text{ Adc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 150\text{ }^{\circ}\text{C}$) (Note 3)	V_{SD}	– –	0.87 0.72	1.0 –	Vdc
Reverse Recovery Time	$(I_S = 3.0\text{ Adc}$, $V_{GS} = 0\text{ Vdc}$, $dI_S/dt = 100\text{ A}/\mu\text{s}$) (Note 3)	t_{rr}	–	35	–	ns
		t_a	–	21	–	
		t_b	–	14	–	
Reverse Recovery Stored Charge		Q_{RR}	–	0.044	–	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$.

4. Switching characteristics are independent of operating junction temperatures.



TYPICAL ELECTRICAL CHARACTERISTICS

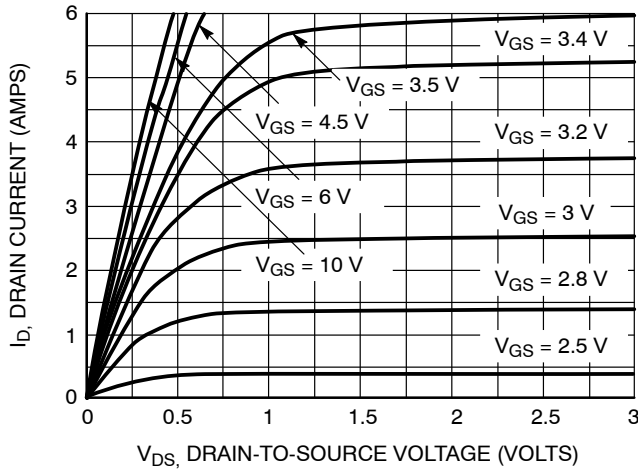


Figure 1. On-Region Characteristics

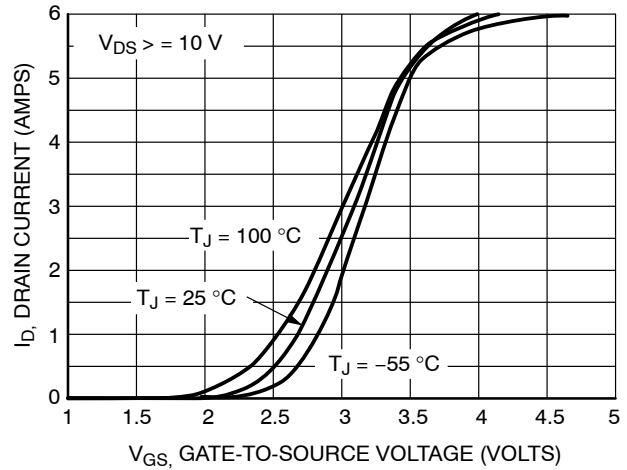


Figure 2. Transfer Characteristics

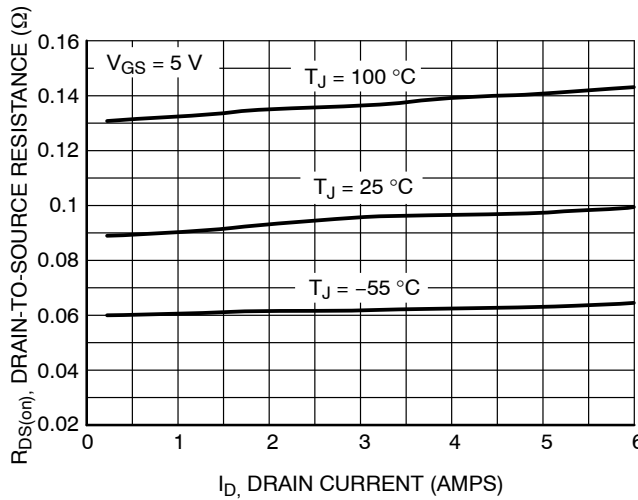


Figure 3. On-Resistance vs. Gate-to-Source Voltage

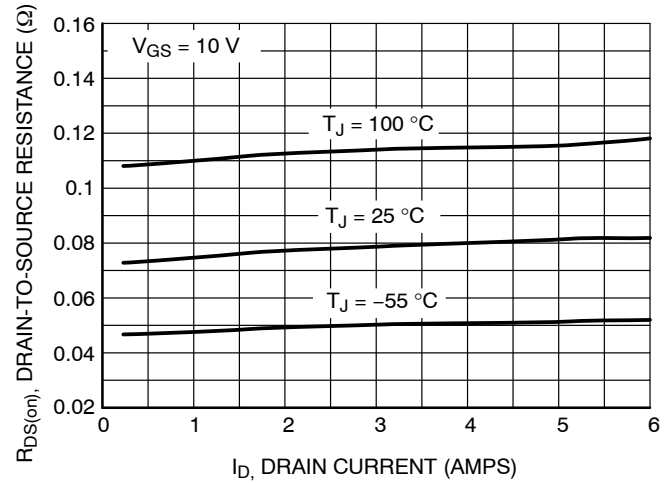


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

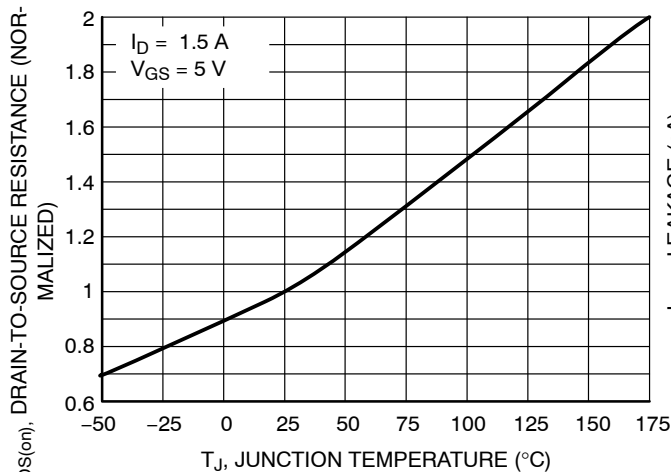


Figure 5. On-Resistance Variation with Temperature

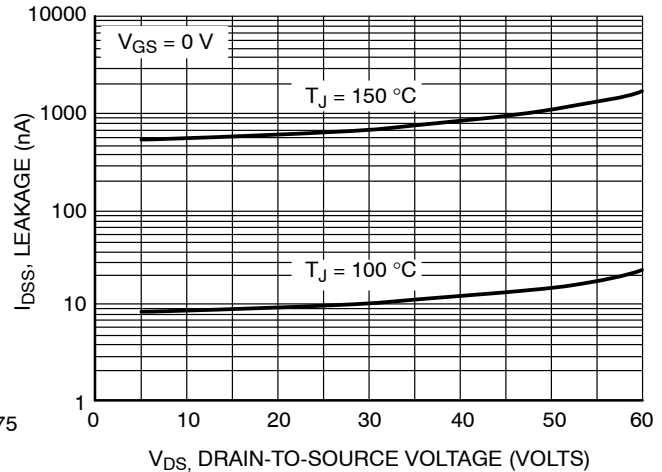


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL ELECTRICAL CHARACTERISTICS

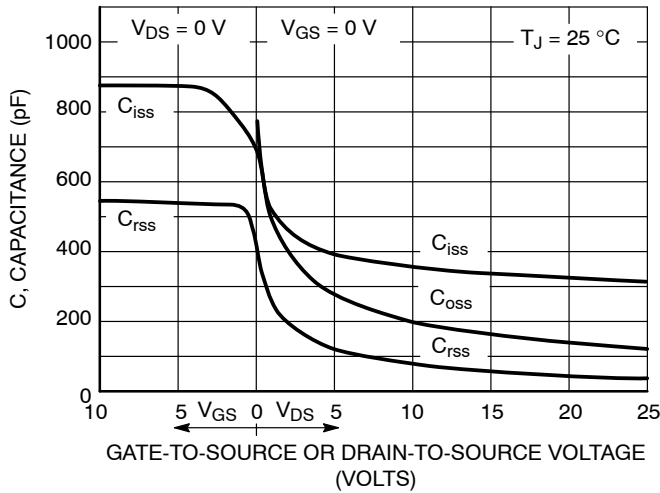


Figure 7. Capacitance Variation

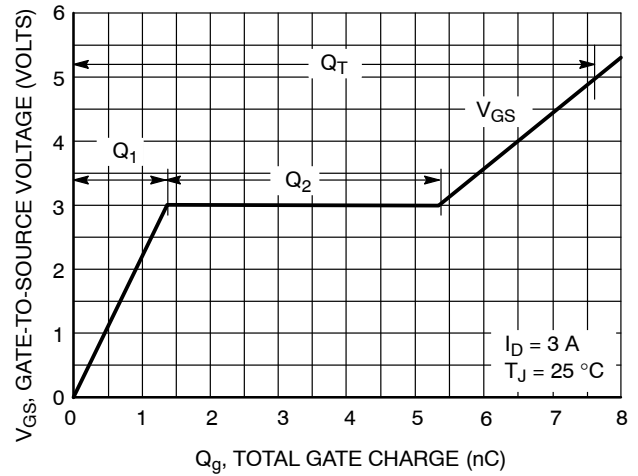


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

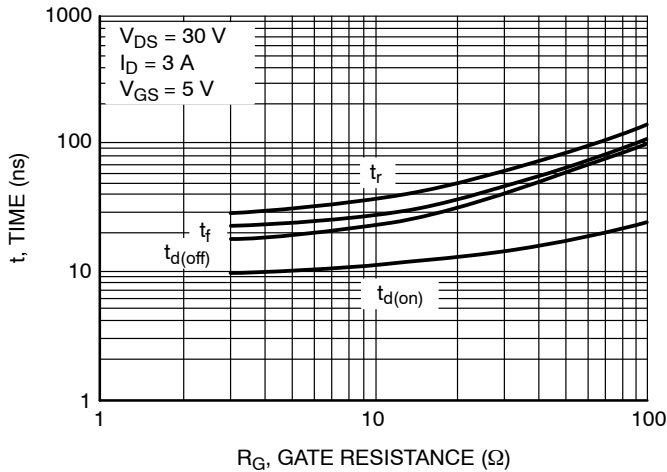


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

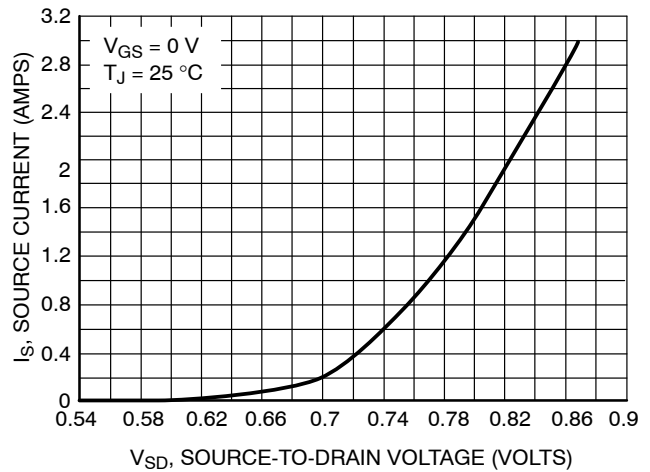


Figure 10. Diode Forward Voltage vs. Current

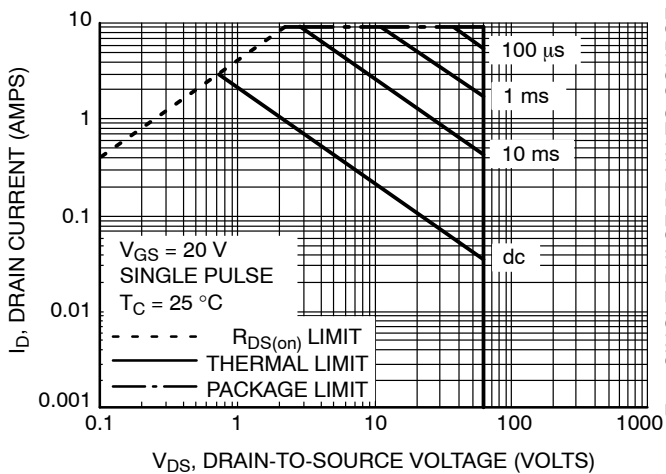


Figure 11. Maximum Rated Forward Biased Safe Operating Area

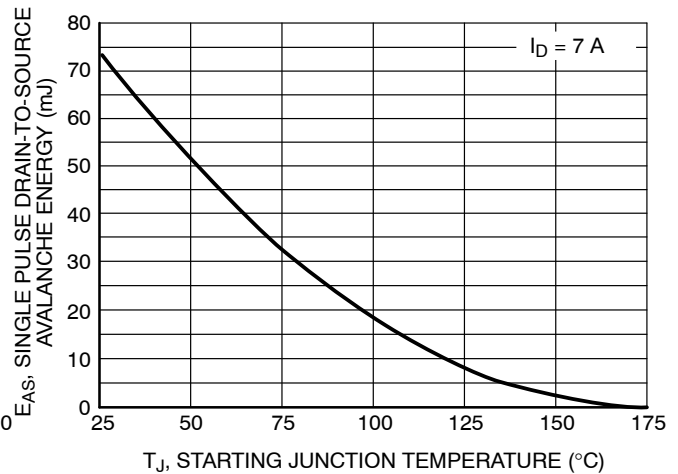


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

NTF3055L108, NVF3055L108

TYPICAL ELECTRICAL CHARACTERISTICS

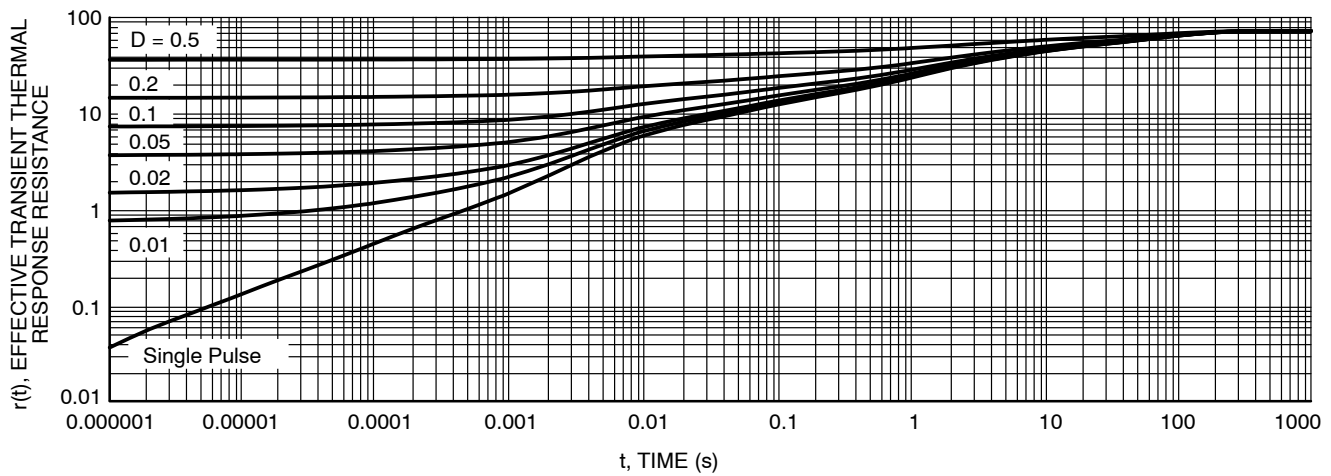


Figure 13. Thermal Response

ORDERING INFORMATION

Device	Package	Shipping [†]
NTF3055L108T1G	SOT-223 (TO-261) (Pb-Free)	1000 / Tape & Reel
NVF3055L108T1G	SOT-223 (TO-261) (Pb-Free)	1000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

REVISION HISTORY

10	Rebranded the document to onsemi format.	10/16/2025
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This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

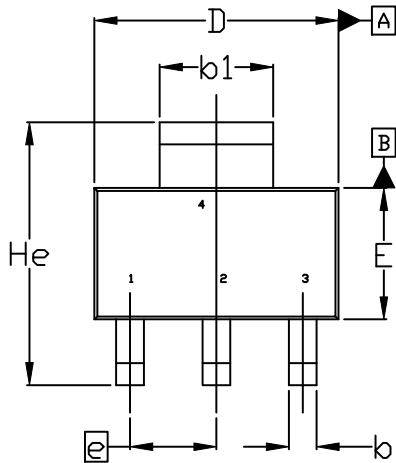




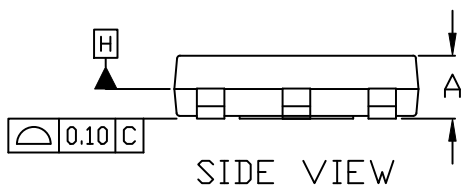
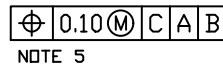
SCALE 1:1

SOT-223 (TO-261)
CASE 318E-04
ISSUE R

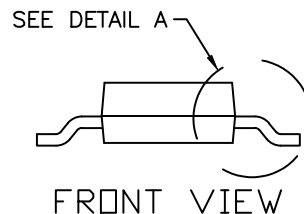
DATE 02 OCT 2018



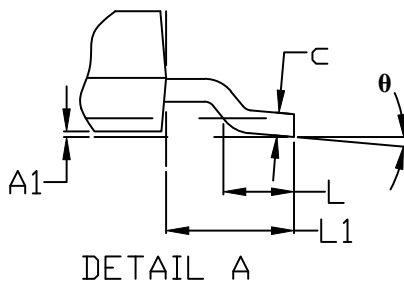
TOP VIEW



SIDE VIEW



FRONT VIEW

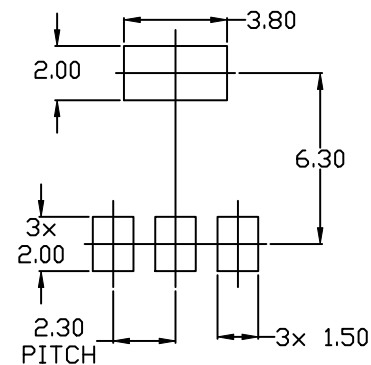


DETAIL A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
4. DATUMS A AND B ARE DETERMINED AT DATUM H.
5. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS b AND b1.

MILLIMETERS			
DIM	MIN.	NOM.	MAX.
A	1.50	1.63	1.75
A1	0.02	0.06	0.10
b	0.60	0.75	0.89
b1	2.90	3.06	3.20
c	0.24	0.29	0.35
D	6.30	6.50	6.70
E	3.30	3.50	3.70
e	2.30 BSC		
L	0.20	---	---
L1	1.50	1.75	2.00
He	6.70	7.00	7.30
θ	0°	---	10°


RECOMMENDED MOUNTING
FOOTPRINT

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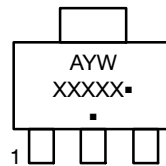
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SOT-223 (TO-261)
CASE 318E-04
ISSUE R

DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

**GENERIC
MARKING DIAGRAM***



A = Assembly Location
 Y = Year
 W = Work Week
 XXXXX = Specific Device Code
 ▪ = Pb-Free Package

(Note: Microdot may be in either location)
 *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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